

Wafer Backlapping Film Applicator

Model
UH108
UH108-8



Ultron Systems' Model UH108 and Model UH108-8 Wafer Backlapping Film Applicators are the ideal benchtop solution for your frontside protection tape application requirements. They offer a high degree of repeatable accuracy and are capable of cutting the film to the edge of the wafer, including the alignment flats, within 0.005 inches in less

than 20 seconds. The standard Model UH108 can accommodate 3, 4, 5, and 6-inch wafers. The Model UH108-8 has 8-inch wafer capability and can also accommodate a smaller wafer for added versatility. A wide range of features and options are available to assure bubble-free lamination to all sizes and types of wafers.

Uniform Film Application

The Model UH108 has an easily adjustable built-in spring-loaded roller assembly, which assures even, bubble-free lamination of the film to the wafer.

Control

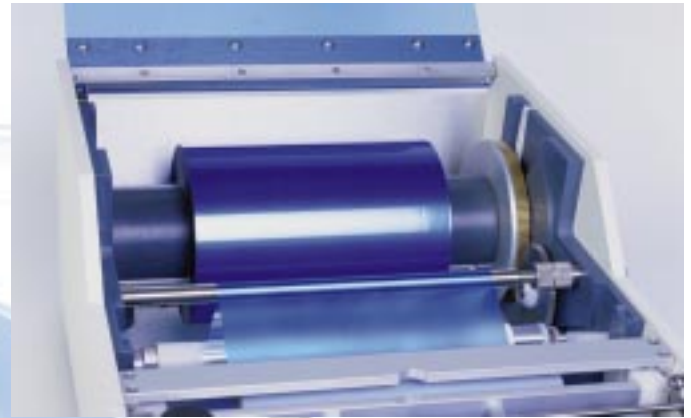
The film cutting system offers adjustable cutting angle, depth and diameter to control the amount of film overhang. Roller pressure is adjustable from the topside of the unit for different film requirements and to accommodate various wafer thicknesses. The Wafer Centration System assures alignment and cutting consistency from wafer to wafer.

Versatility

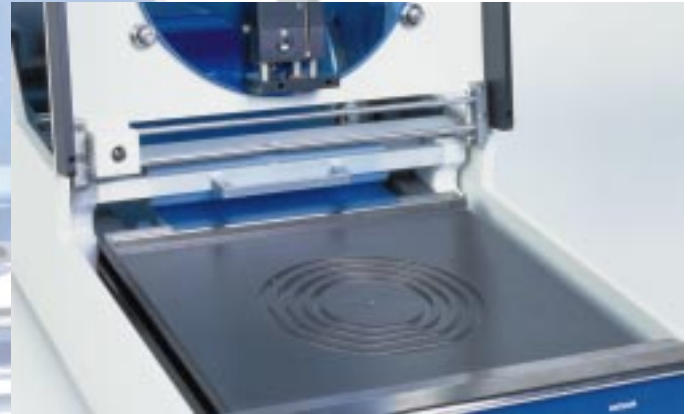
Adjustable alignment pins accommodate any wafer size. The cutter assembly is adjustable for either a contact cut - for wafers with alignment flat(s) or non-contact cut - for wafers with an alignment notch. In addition, the Model UH108 uses a spring-loaded tensioner bar to prevent wafer stress due to film stretch.

Take-up Roller Assembly Option

A gear-driven take-up Roller Assembly is available for use with protective layer-backed films. This assembly automatically winds the protective layer onto a plastic core for easy handling and disposal.



Take-up Roller Assembly Option



Close-up of Circular Cutter and Workstage

Static Eliminator Option

A static ionization bar is available to prevent static build-up caused from the film unwinding or from the separation of the film from the protective layer.

Edge-Contact Stage Option

For applications that require that the face of the wafer not contact the surface of the workstage, this stage will suspend the wafer by holding it in place via a narrow vacuum groove around its outside edge. An adjustable air pressure support fills the cavity to prevent the wafer from bowing during film lamination.

SPECIFICATIONS

MODEL UH108/UH108-8

Height:	8.5 inches
Width:	14.5 inches
Depth:	28.5 inches
Weight:	48 lbs.

Voltage: 110 or 220 VAC; 50/60 Hz
Vacuum: 25mm Hg

*Ultron Systems offers a complete line of adhesive plastic films for wafer/die handling.
Please call for additional information and samples.*